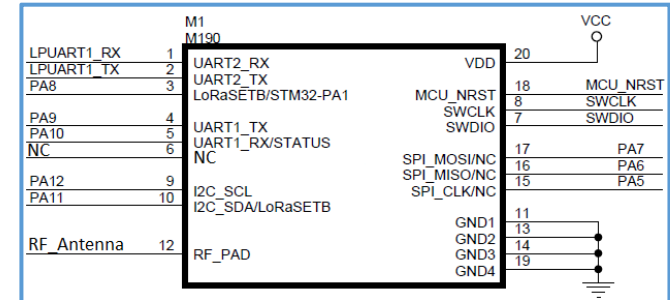
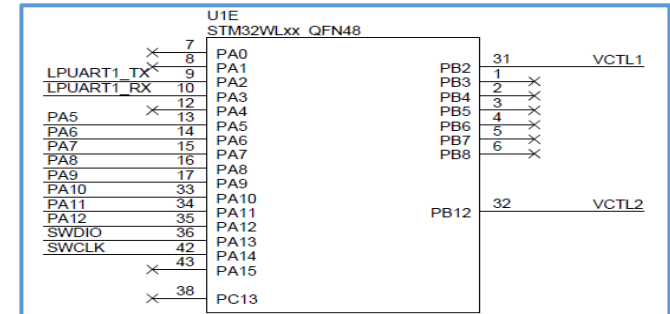
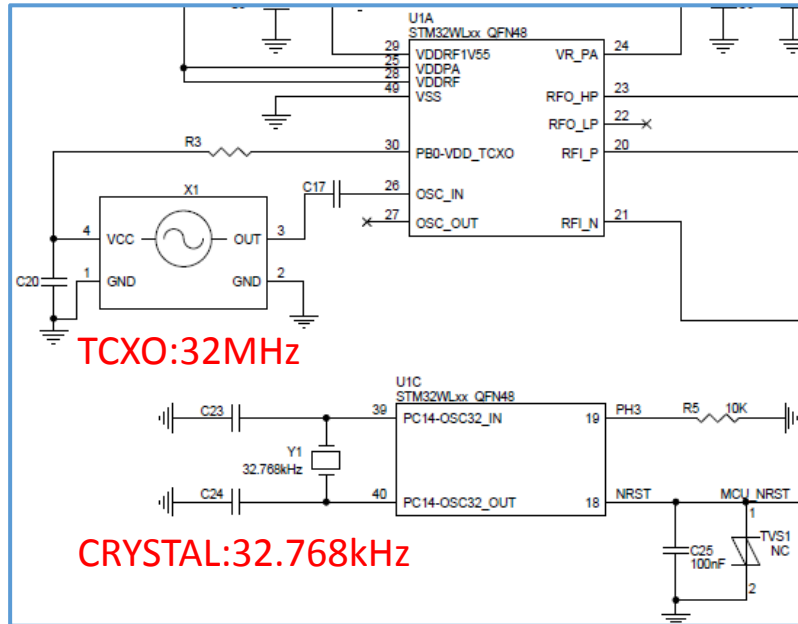
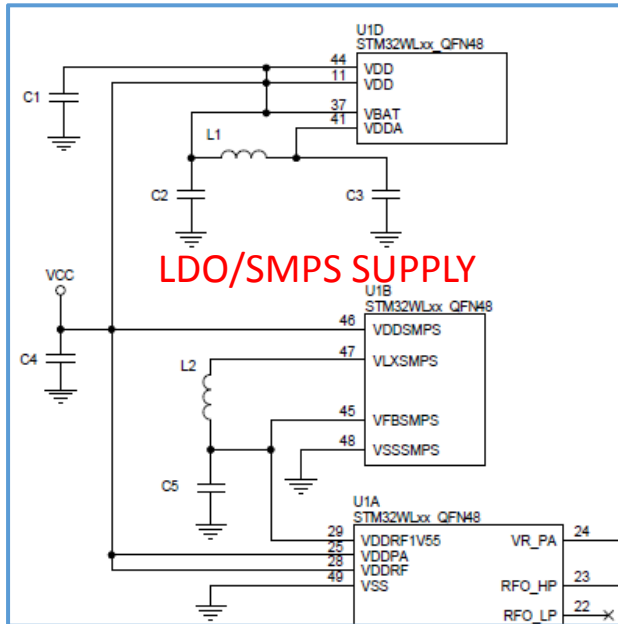


M19X Module Development Guide — Hardware

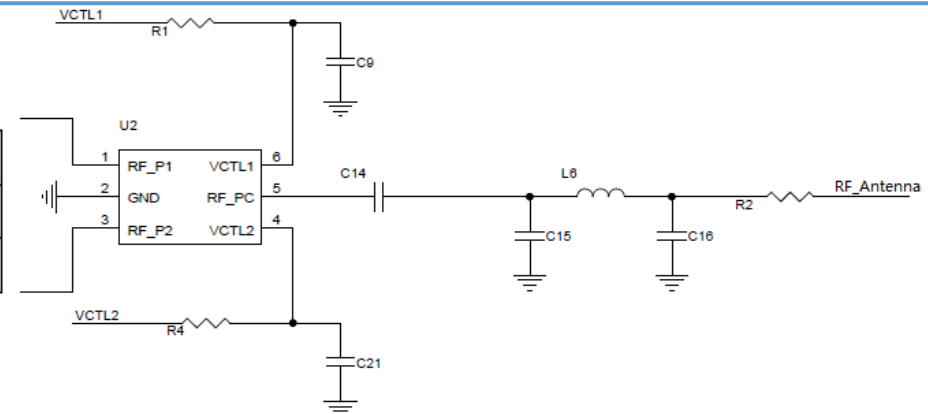


Hardware Design Schematic



SPDT Switch Truth Table

VCTL1 (Pin 6)	VCTL2 (Pin 4)	INPUT to OUTPUT1 Path	INPUT to OUTPUT2 Path
1	0	Isolation	Insertion loss
0	1	Insertion loss	Isolation



Pin Function Description(Module vs MCU)

M190 Pin	MCU Pin name	Pin type	I/O structure	Alternate functions	Additional functions	M190 Pin	MCU Pin name	Pin type	I/O structure	Alternate functions	Additional functions
1	PA2	I/O	FT_a	LSCO, TIM2_CH3, USART2_TX, LPUART1_TX, COMP2_OUT, DEBUG_PWR_LDORDY, CM4_EVENTOUT	LSCO	11	VSS VSSSMPS	S	-	-	-
2	PA3	I/O	FT_a	TIM2_CH4, I2S2_MCK, USART2_RX, LPUART1_RX, CM4_EVENTOUT	-	12	-	-	-	-	-
3	PA8	I/O	FT_a	MCO, TIM1_CH1, SPI2_SCK/I2S2_CK, USART1_CK, LPTIM2_OUT, CM4_EVENTOUT	-	13	VSS VSSSMPS	S	-	-	-
4	PA9	I/O	FT_fa	TIM1_CH2, SPI2_NSS/I2S2_WS, I2C1_SCL, SPI2_SCK/I2S2_CK, USART1_TX, CM4_EVENTOUT	-	14	VSS VSSSMPS	S	-	-	-
5	PA10	I/O	FT_fa	RTC_REFIN, TIM1_CH3, I2C1_SDA, SPI2_MOSI/I2S2_SD, USART1_RX, DEBUG_RF_HSE32RDY, TIM17_BKIN, CM4_EVENTOUT	COMP1_INM, COMP2_INM, DAC_OUT1, ADC_IN6	15	PA5	I/O	FT	TIM2_CH1, TIM2_ETR, SPI2_MISO, SPI1_SCK, DEBUG_SUBGHZSPI_SCKOUT, LPTIM2_ETR, CM4_EVENTOUT	-
6	NC	-	-	-	-	16	PA6	I/O	FT	TIM1_BKIN, I2C2_SMBA, SPI1_MISO, LPUART1_CTS, DEBUG_SUBGHZSPI_MISOOUT, TIM16_CH1, CM4_EVENTOUT	-
7	PA13	I/O	FT_a	JTMS-SWDIO, I2C2_SMBA, IR_OUT, CM4_EVENTOUT	ADC_IN9	17	PA7	I/O	FT_fa	TIM1_CH1N, I2C3_SCL, SPI1_MOSI, COMP2_OUT, DEBUG_SUBGHZSPI_MOSIOUT, TIM17_CH1, CM4_EVENTOUT	-
8	PA14	I/O	FT_a	JTCK-SWCLK, LPTIM1_OUT, I2C1_SMBA, CM4_EVENTOUT	ADC_IN10	18	NRST	I/O	FT	-	-
9	PA12	I/O	FT_fa	TIM1_ETR, LPTIM3_IN1, I2C2_SCL, SPI1_MOSI, RF_BUSY, USART1_RTS, CM4_EVENTOUT	ADC_IN8	19	VSS VSSSMPS	S	-	-	-
10	PA11	I/O	FT_fa	TIM1_CH4, TIM1_BKIN2, LPTIM3_ETR, I2C2_SDA, SPI1_MISO, USART1_CTS, DEBUG_RF_NRESET, CM4_EVENTOUT	COMP1_INM, COMP2_INM, ADC_IN7	20	VDD VDDPA VDDRF VBAT VDDSMPS	S	-	-	-

Electrical characteristics

Item	Conditions	Min	Typ	Max	Unit
Operating Voltage	All Band	2.0	3.3	3.6	V
Supply Current	TX , +22dBm	-	120	-	mA
	TX , +17dBm	-	78	-	mA
	RX	-	9	-	mA
	Standby (Class C)	-	8	-	mA
	Sleep (Class A)	1.1	1.5	1.8	μA
Operating Frequency Band	Low Band	430	-	510	MHz
	High Band	862	-	932	MHz
Operating Temperature		-40	-	85	°C
Working Humidity	No-condensation	10%	-	90%	RH
Transmission characteristics	LoRa Mode, Carrier Output, PA_BOOST ON, 25±2°C				
MAX. Output Power	-	21.0	21.6	22.0	dBm
Second Harmonic			-40	-	dBm
Receive Characteristics	PER = 1% , CR = 4/5 , CRC ON , Preamble Length = 12 , Packet Length = 10				
Receive Sensitivity	SF12 , 125kHz	-	-139	-	dBm
Frequency Characteristics	Frequency Stability: ±2ppm@-40°C~85°C				

RF_TX/RX Specifications

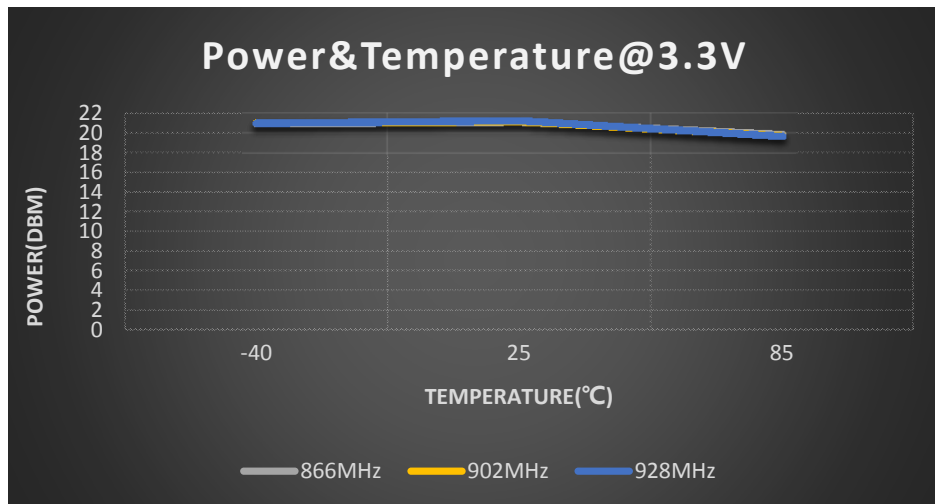
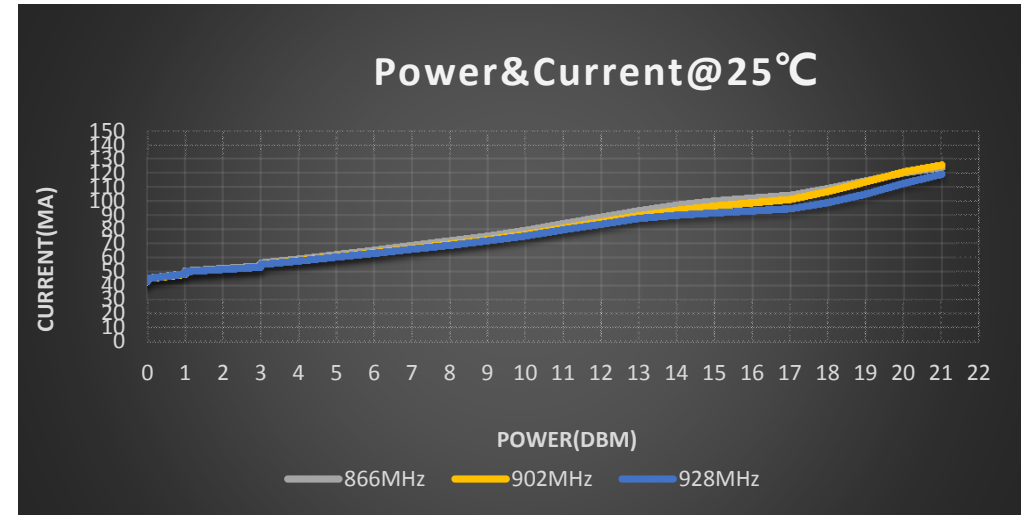
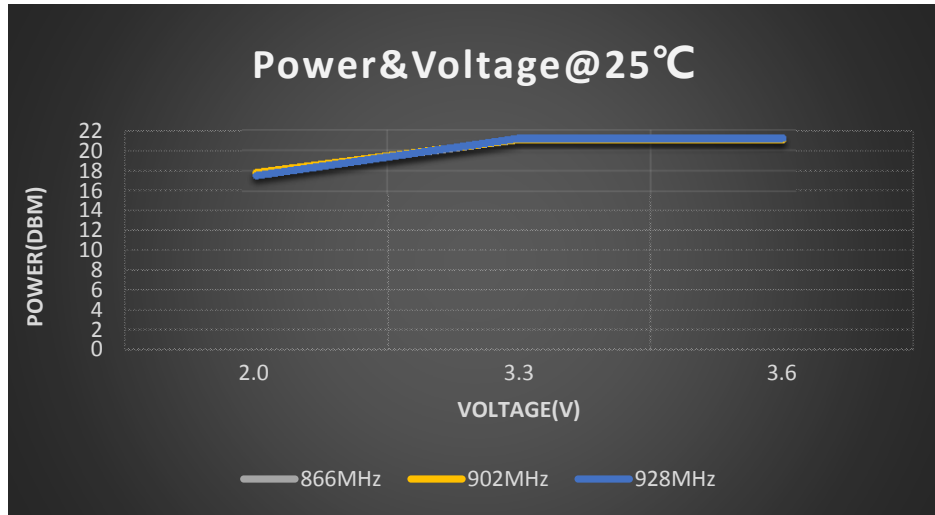
Sub-GHz radio transmit high output power

V _{DDPA} supply (V)	Transmit output power (dBm)
3.3	+ 22
2.7	+ 20
2.4	+ 19
1.8	+ 16

Sub-GHz radio receive mode specifications

Symbol	Description	Conditions	Min	Typ	Max	Unit
RXS_LB	Sensitivity LoRa, RX boosted gain, split RF paths for RX and Tx, RF switch insertion loss excluded	BW = 125 kHz, SF = 7	-	-125	-	dBm
		BW = 125 kHz, SF = 12	-	-138	-	
		BW = 250 kHz, SF = 7	-	-122	-	
		BW = 250 kHz, SF = 12	-	-135	-	
		BW = 500 kHz, SF = 7	-	-118	-	
		BW = 500 kHz, SF = 12	-	-130	-	

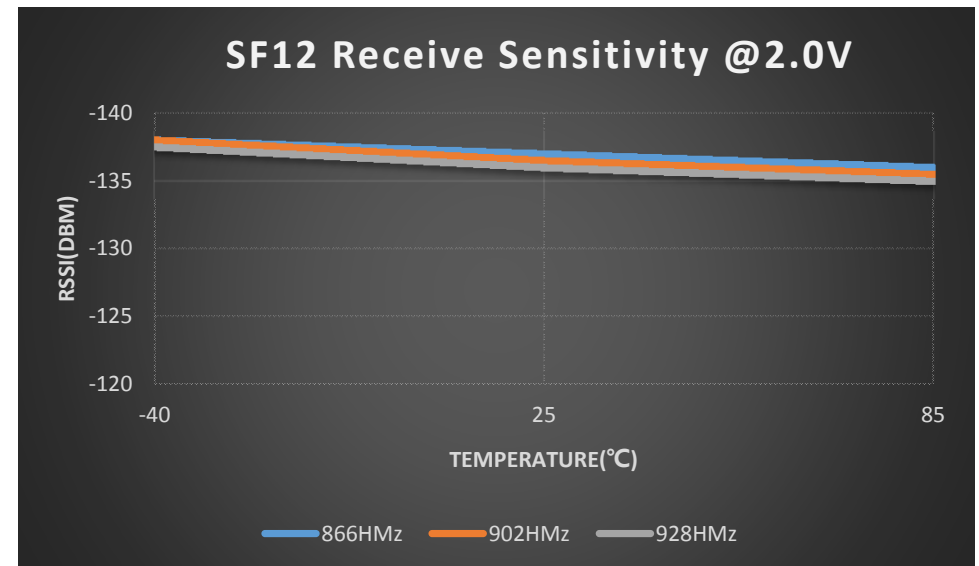
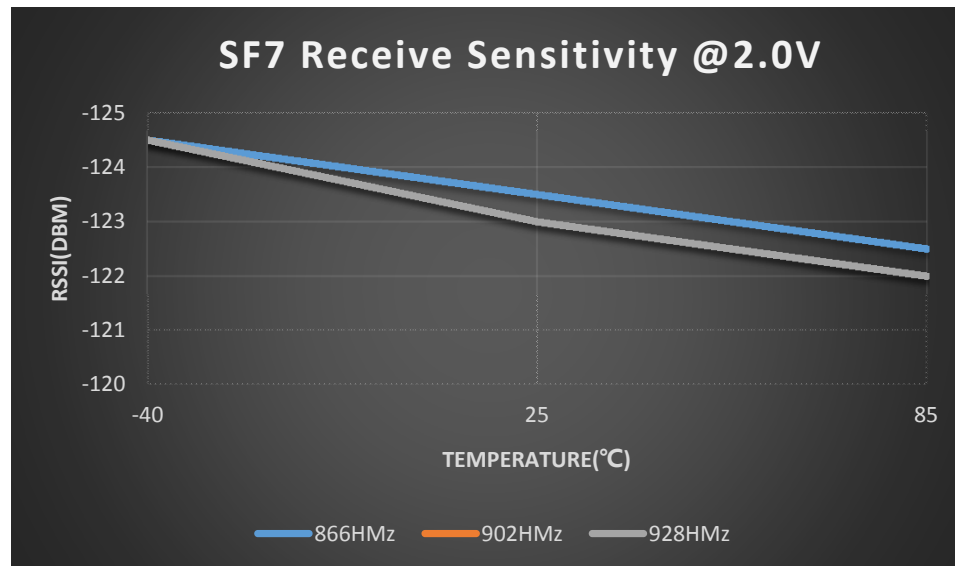
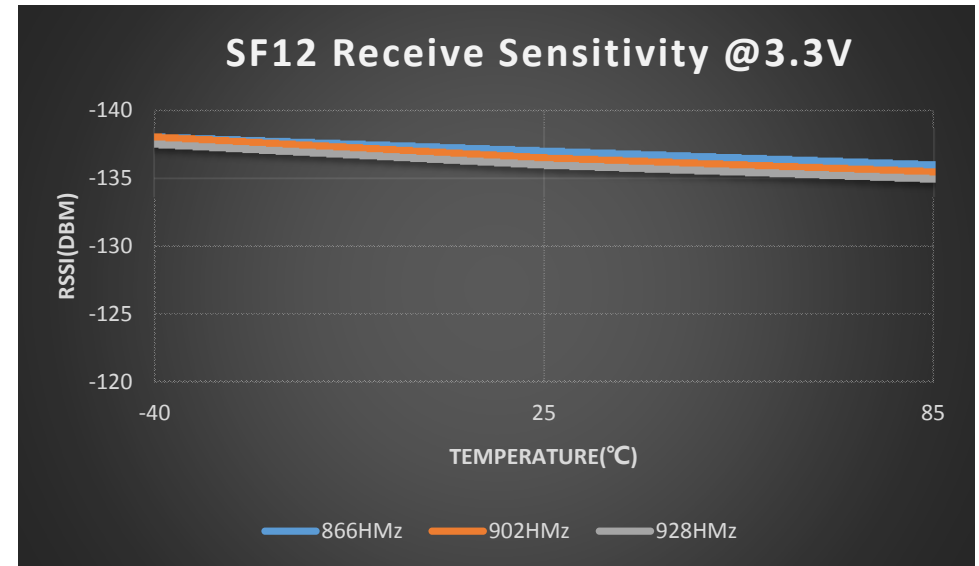
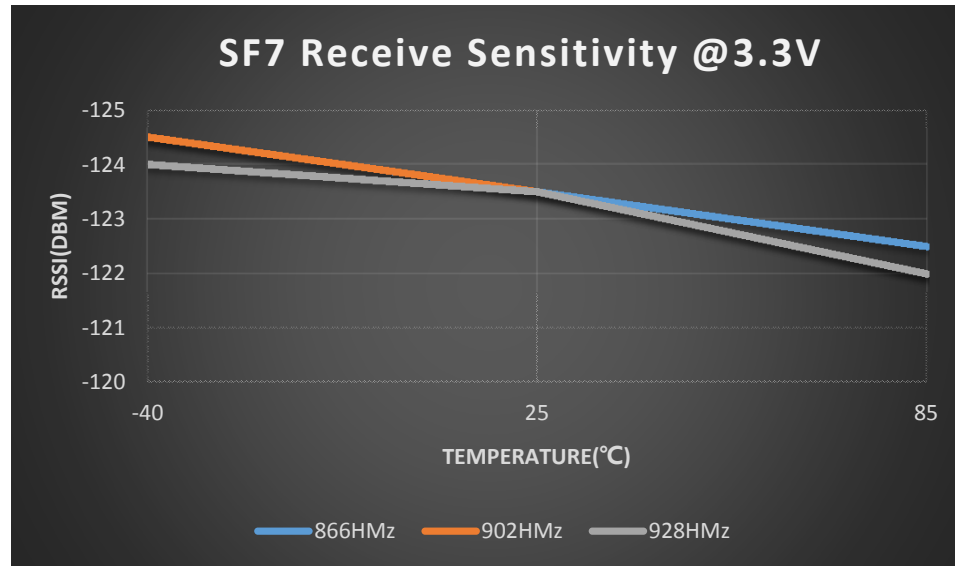
Transmit Test Data



Conducted Spurious Emission

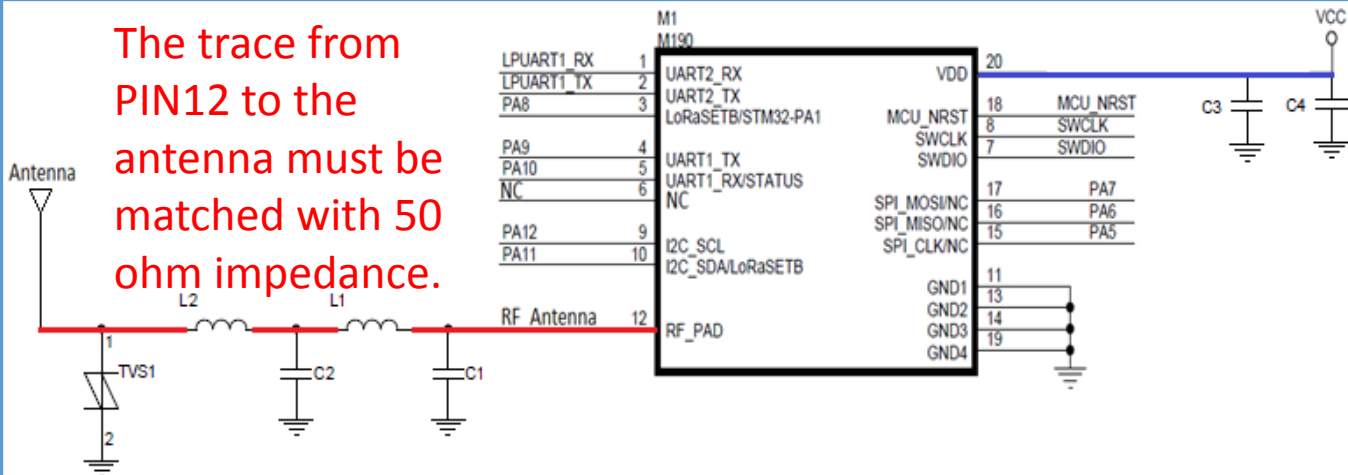
Operating conditions:3.3V, 25°C, 22dBm						
Frequency	866MHz		902MHz		928MHz	
Harmonic	2nd	3nd	2nd	3nd	2nd	3nd
1# (dBm)	-40.81	-50.18	-43.28	-48.55	-41.43	-48.05
Margin (dB)	10.81	20.18	13.28	18.55	11.43	18.05
2# (dBm)	-40.75	-50.62	-43.25	-48.47	-41.78	-49.01
Margin (dB)	10.75	20.62	13.25	18.47	11.78	19.01

Receive Sensitivity Test Data



Hardware Design Reference

The trace from PIN12 to the antenna must be matched with 50 ohm impedance.

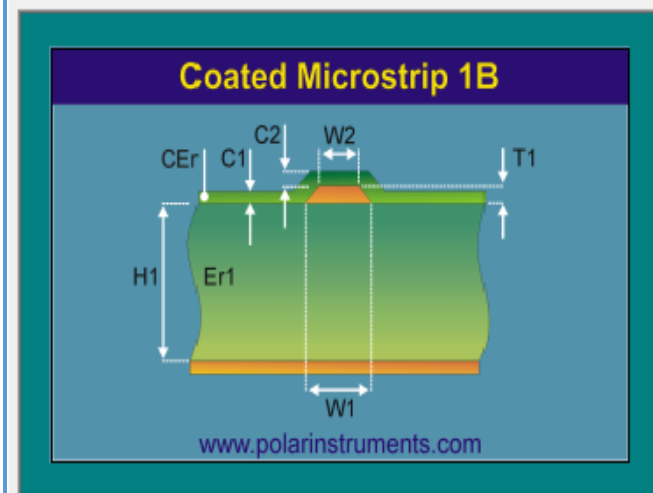


The power supply capacity of the burst current is not less than 150mA.

If it is powered by a capacity battery, please add a super capacitor.

The safe power supply voltage range is 2.0~3.6V.

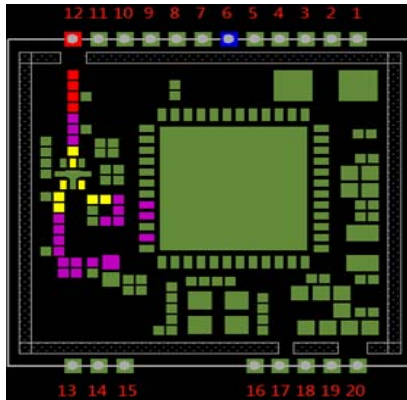
You can use Polar Si9000 to simulate and calculate the trace width, which is related to the PCB dielectric(ϵ_r), trace thickness(T_1) and the distance(H_1) between the adjacent layer GND . And add more ground holes on both sides of the trace.



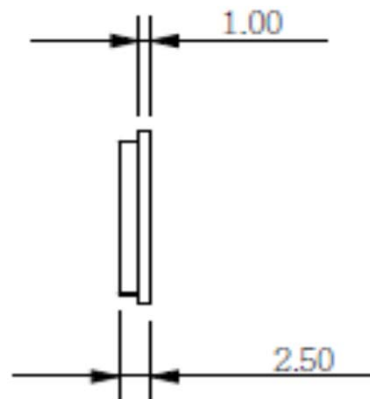
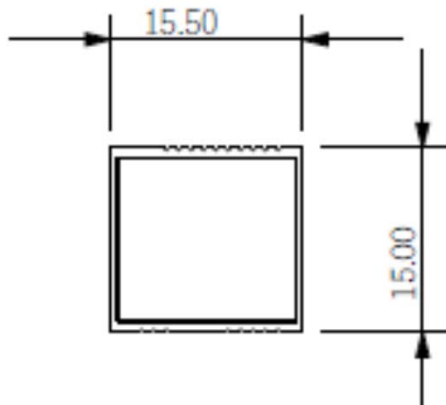
			Tolerance	Minimum	Maximum	
Substrate 1 Height	H1	3.6500	+/-	0.0000	3.6500	3.6500 Calculate
Substrate 1 Dielectric	Er1	3.8500	+/-	0.0000	3.8500	3.8500 Calculate
Lower Trace Width	W1	6.8221	+/-	0.0000	6.8221	6.8221
Upper Trace Width	W2	5.8221	+/-	0.0000	5.8221	5.8221 Calculate
Trace Thickness	T1	0.6900	+/-	0.0000	0.6900	0.6900 Calculate
Coating Above Substrate	C1	0.8000	+/-	0.0000	0.8000	0.8000
Coating Above Trace	C2	0.5000	+/-	0.0000	0.5000	0.5000
Coating Dielectric	CEr	3.3000	+/-	0.0000	3.3000	3.3000
Impedance	Zo	50.00		0.00	0.00	0.00 Calculate

Structure and Package

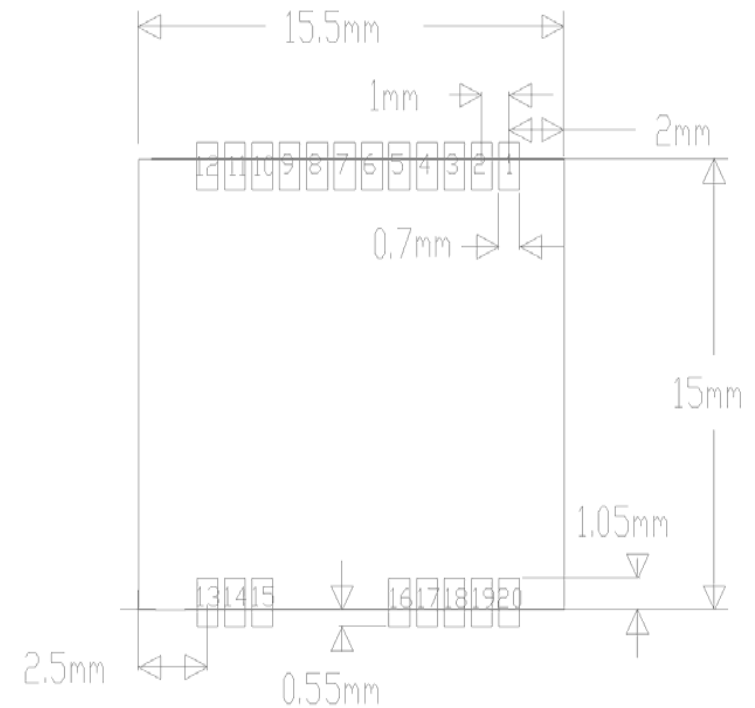
1mm Pitch Htamp Hole Pads



Structure Size



Package



Thank you!